In microelectronics, a three-dimensional integrated circuit (3D IC) is an integrated circuit manufactured by stacking silicon wafers or dies and interconnecting them vertically using, for instance, through-silicon vias (TSVs) or Cu-Cu connections, so that they behave as a single device to achieve performance improvements at reduced power and smaller footprint than conventional two-dimensional processes. While a 2.5-dimensional integrated circuit (2.5D IC) is a package with an active electronic component (for example, a die or a chip) stacked on an interposer through conductive bumps or TSVs.

The global 3D IC and 2.5D IC market is estimated to grow at the highest CAGR during the forecast period. In terms of geographic regions, Asia-Pacific acquired largest market for 3D IC and 2.5D IC in 2018. The large market in Asia-Pacific is owing to the broad scope of 3D IC and 2.5D IC packages in various consumer electronics applications, particularly in smartphones and tablets.

The global 3D IC and 2.5D IC market was valued at xx million US$ in 2018 and will reach xx million US$ by the end of 2025, growing at a CAGR of xx% during 2019-2025. This report focuses on 3D IC and 2.5D IC volume and value at global level, regional level and company level. From a global perspective, this report represents overall 3D IC and 2.5D IC market size by analyzing historical data and future prospect. Regionally, this report categorizes the production, apparent consumption, export and import of 3D IC and 2.5D IC in North America, Europe, China, Japan, Southeast Asia and India.

For each manufacturer covered, this report analyzes their 3D IC and 2.5D IC manufacturing sites, capacity, production, ex-factory price, revenue and market share in global market.

The following manufacturers are covered:
TSMC (Taiwan)
Samsung (South Korea)
Toshiba (Japan)
ASE Group (Taiwan)
Amkor (US)
UMC (Taiwan)
Stmicroelectronics (Switzerland)
Broadcom (US)
Intel (US)
Jiangsu Changjiang Electronics (China)
Segment by Regions
North America
Europe
China
Japan
Southeast Asia
India
Segment by Type
3D wafer-level chip-scale packaging
3D TSV
2.5D
Segment by Application
Consumer electronics
Telecommunication
Industry sector
Automotive
Military and Aerospace
Smart technologies
Medical devices

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